

Surface Mount Schottky Barrier Rectifier

| Parameter | Value | Unit |
|-------------|--------|------|
| V_{RRM} | 20~200 | V |
| $I_{F(AV)}$ | 5.0 | A |



DO-214AB/SMC

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability

Applications

- For use in low-voltage, high-frequency inverters, free-wheeling applications, DC/DC converters, and polarity protection circuits.

Absolute Maximum Ratings and Characteristics (Ta=25°C unless otherwise noted)

| Parameter | Symbol | SS52 | SS54 | SS56 | SS58 | SS510 | SS512 | SS515 | SS520 | Units |
|---|-----------------|------------|------|------|------|-------|-------|-------|-------|-------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 20 | 40 | 60 | 80 | 100 | 120 | 150 | 200 | V |
| Maximum RMS voltage | V_{RMS} | 14 | 28 | 42 | 56 | 70 | 84 | 105 | 140 | V |
| Maximum DC Blocking Voltage | V_{DC} | 20 | 40 | 60 | 80 | 100 | 120 | 150 | 200 | V |
| Maximum Average Forward Rectified Current | $I_{F(AV)}$ | 5.0 | | | | | | | | A |
| Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) | I_{FSM} | 150 | | | | | | | | A |
| Max Instantaneous Forward Voltage at 5A | V_F | 0.45 | 0.55 | 0.70 | | 0.85 | | 0.9 | | V |
| Maximum DC Reverse Current at Rated DC Reverse Voltage | I_R | 0.5 5 | | | | | | | | mA |
| Typical Junction Capacitance ⁽¹⁾ | C_j | 600 | | | 400 | | | | | pF |
| Typical Thermal Resistance ⁽²⁾ | $R_{\theta JA}$ | 35 | | | | | | | | °C/W |
| Operating Junction Temperature Range | T_j | -55 ~ +150 | | | | | | | | °C |
| Storage Temperature Range | T_{stg} | -55 ~ +150 | | | | | | | | °C |

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Typical characteristics

Fig.1 Forward Current Derating Curve

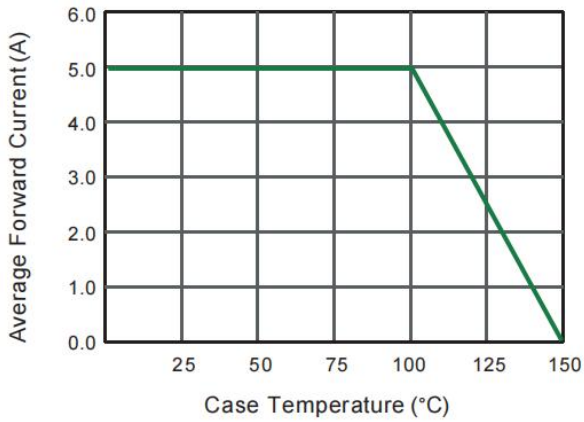


Fig.2 Typical Reverse Characteristics

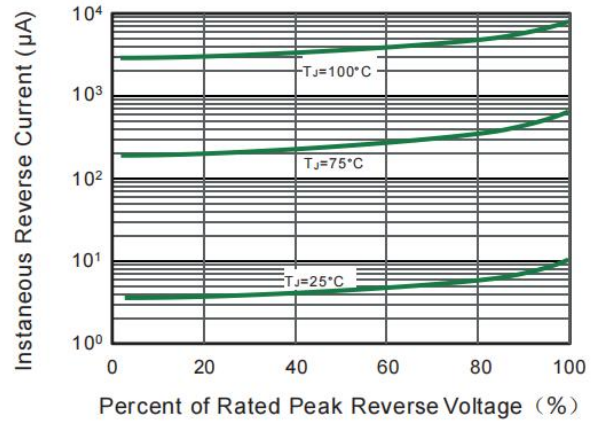


Fig.3 Typical Forward Characteristic

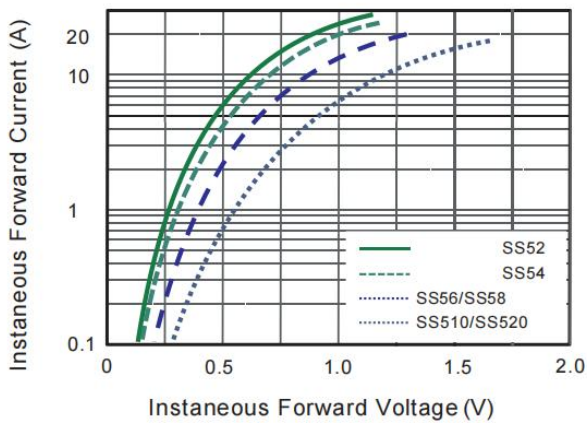


Fig.4 Typical Junction Capacitance

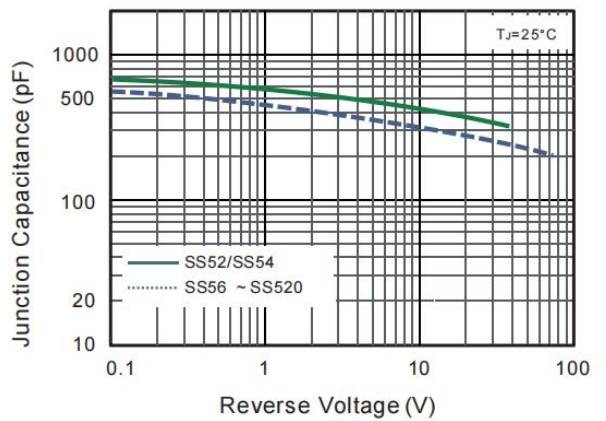


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

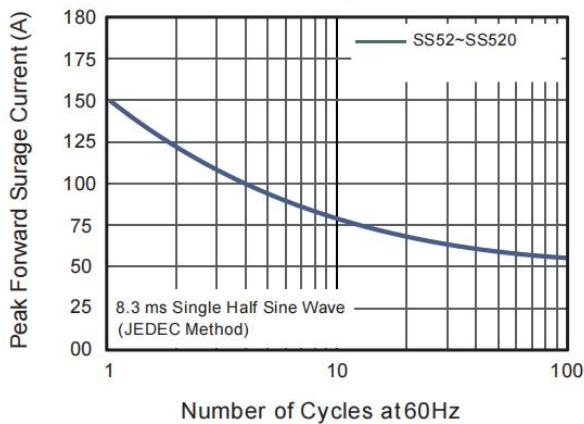
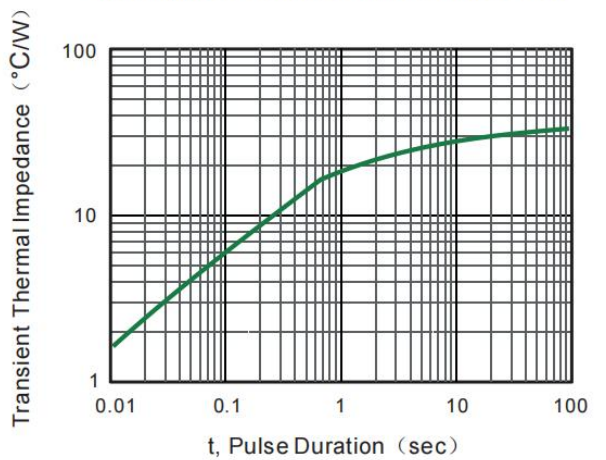


Fig.6- Typical Transient Thermal Impedance



Package Outlines

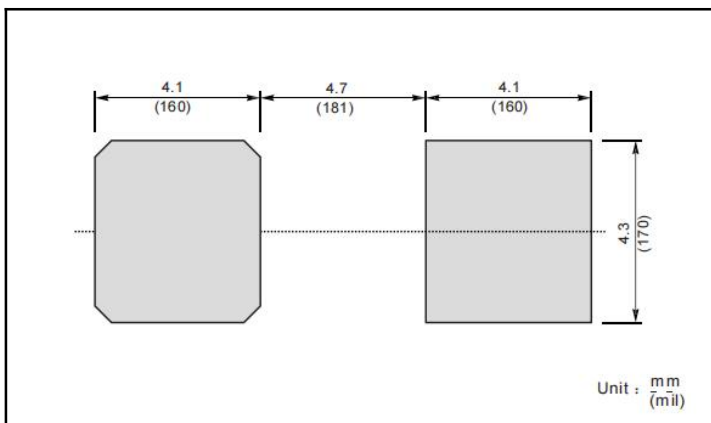
Plastic surface mounted package; 2 leads

DO-214AB/SMC

SMC mechanical data

| UNIT | | A | E | D | B | A ₁ | C | L | b |
|------|-----|------|-----|-----|-----|----------------|------|-----|------|
| mm | max | 2.62 | 7.1 | 6.2 | 8.3 | 0.21 | 0.31 | 1.6 | 3.25 |
| | min | 2.00 | 6.6 | 5.6 | 7.7 | 0.05 | 0.15 | 0.9 | 2.75 |
| mil | max | 103 | 280 | 244 | 327 | 8.3 | 12 | 63 | 128 |
| | min | 79 | 260 | 220 | 303 | 2.0 | 5.9 | 35 | 108 |

The recommended mounting pad size



Marking

| Type number | Marking code |
|-------------|--------------|
| SS52 | SS52 |
| SS54 | SS54 |
| SS56 | SS56 |
| SS58 | SS58 |
| SS510 | SS510 |
| SS512 | SS512 |
| SS515 | SS515 |
| SS520 | SS520 |

***Important Usage Information and Disclaimer**

The specifications of Zhuhai Hypersemi Co., Ltd. products are not guarantees of product characteristics. They reflect typical performance expected in standard applications, which may vary with specific uses. Users must conduct prior testing for their applications and make necessary adjustments.

Users are responsible for the safety of applications utilizing our products and must implement adequate safety measures to prevent physical injury, fire, or other risks in case of product failure. It is the user's duty to ensure that application designs comply with all applicable laws and standards. Our products must not be used in any applications where a product failure could reasonably result in personal injury, unless specifically authorized in a signed document by Zhuhai Hypersemi Co., Ltd.

No representations or warranties are made regarding the accuracy or completeness of this information, including any claims of non-infringement of third-party intellectual property rights. Zhuhai Hypersemi Co., Ltd. assumes no liability for any applications or uses of its products and does not grant any licenses to its intellectual property rights or those of others. We also make no claims regarding non-infringement of third-party intellectual property rights that may arise from applications.

Due to technical requirements, our products may contain hazardous substances. For details, please contact your nearest sales office. This document replaces all previous information and may be updated. We reserve the right to make changes.